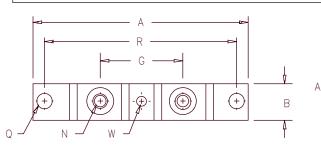
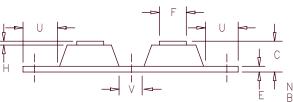
Schottky PowerMod











Common Cathode Baseplate D=Doubler

Baseplate: Nickel plated copper

Dim. Inches		Millimeters		
Min.	Max.	Min.	Max.	Notes
B 0.700 C E 0.120 F 0.490 G 1.375 H 0.010 N Q 0.275 R 3.150 U 0.600 V 0.312	0.510 BSC 0.290 BSC	34.92 0.25 6.99 80.0 15.24 7.92	12.95 2 BSC 7.37 1 BSC	1/4-28 Dia.

Microsemi Catalog Number	Industry Part Number	Working Peak Reverse Voltage	
CPT20130* CPT20135*	MBR20030CT 200CNQ035 224CNQ035 MBR20035CT	30V 35V	30V 35V
CPT20140*	200CNQ040 224CNQ040 MBR20040CT	40V	40V
CPT20145*	200CNQ045 224CNQ045 MBR20045CT	45V	45V
*Add Sut	fix A for Com	mon Anode, D fo	r Doubler

- Schottky Barrier Rectifier
- Guard Ring Protection
- 200 Amperes/30 to 45 Volts
- 150° C Junction Temperature
- Reverse Energy Tested
- ROHS Compliant

Electrical Characteristics

|F(AV) 200 Amps Average forward current per pkg Average forward current per leg F(AV) 100 Amps İFSM Maximum surge current per leg 2000 Amps Maximum repetitive reverse current per leg | R(OV) 2 Amps VFM 0.68 Volts Max peak forward voltage per leg V_{FM} Max peak forward voltage per leg 0.64 Volts ^IRM 1100mA Max peak reverse current per leg Max peak reverse current per leg ^IRM 4.0mA C_J 5500pF Typical junction capacitance

 ^{T}C = 99°C, Square wave, $^{R}\Theta JC$ = .20°C/W ^{T}C = 99°C, Square wave, $^{R}\Theta JC$ = .40°C/W

8.3ms, half sine, TJ = 125°C f = 1 KHZ, 25°C FM = 200A: TJ = 25°C* FM = 200A: TJ = 125°C* VRRM, TJ = 125°C* VRRM, TJ = 25°C*

 $VR = 5.0V, TC = 25^{\circ}C$

*Pulse test: Pulse width 300 usec, Duty cycle 2%

Thermal and Mechanical Characteristics

TSTG Storage temp range -55°C to 150°C ΤJ -55°C to 150°C 0.40°C/W Junction to case Operating junction temp range R OJC Max thermal resistance per leg Recs Typical thermal resistance (greased) 0.08°C/W Case to sink 35-40 inch pounds Terminal Torque Mounting Base Torque (outside holes) Mounting Base Torque (center hole) 30-40 inch pounds 8-10 inch pounds center hole must be torqued first Weight 2.8 ounces (75 grams) typical



CPT20130 - CPT20145

Figure 1 Maximum Forward Characteristics — Per Lea

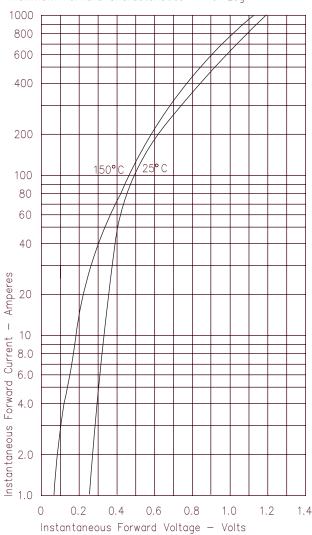


Figure 3
Typical Junction Capacitance — Per Leg

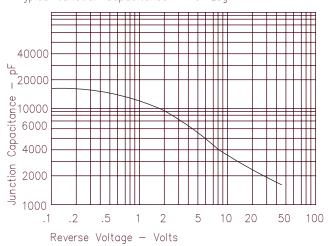


Figure 4 Forward Current Derating — Per Leg

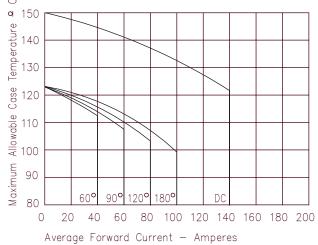


Figure 2 Typical Reverse Characteristics — Per Leg

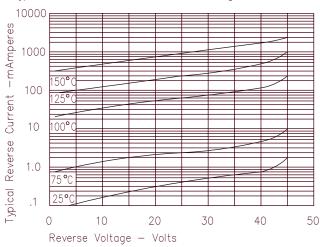
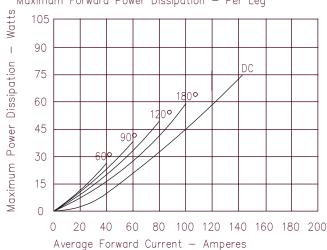


Figure 5
Maximum Forward Power Dissipation — Per Leg





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